



Material Content Data Sheet



Sales Product Name		BTS5030-1EJA		Issued		29. August 2013		
MA#		MA001136574						
Package		PG-DSO-8-43		Weight*		84.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.062	2.44	2.44	24422	24422
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		111	
	non noble metal	zinc	7440-66-6	0.038	0.04		445	
	non noble metal	iron	7439-89-6	0.752	0.89		8905	
wire	non noble metal	copper	7440-50-8	30.529	36.16	37.10	361569	371030
	non noble metal	copper	7440-50-8	0.450	0.53	0.53	5327	5327
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.11		1145
plastics	plastics	epoxy resin	-	4.447	5.27		52670	
	inorganic material	silicondioxide	60676-86-0	43.795	51.88	57.26	518685	572500
leadfinish	non noble metal	tin	7440-31-5	0.814	0.96	0.96	9639	9639
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8598	8598
glue	plastics	epoxy resin	-	0.125	0.15		1485	
	noble metal	silver	7440-22-4	0.591	0.70	0.85	6999	8484
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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